

ON Semiconductor®

## FQU5N50CTU-WS

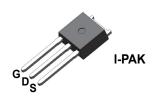
# N-Channel QFET<sup>®</sup> MOSFET 500 V, 4.0 A, 1.4 $\Omega$

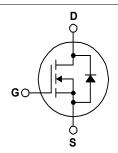
#### **Features**

- 4.0 A, 500 V,  $R_{DS(on)}$  = 1.4  $\Omega$  @ $V_{GS}$  = 10 V
- Low Gate Charge (Typ. 18 nC)
- Low Crss (Typ. 15 pF)
- Fast Switching
- 100% Avalanche Tested
- · Improved dv/dt Capability

#### Description

This N-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQU5N50CTU-WS	Units	
V <sub>DSS</sub>	Drain-Source Voltage		500	V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C	C)	4.0	Α	
	- Continuous (T <sub>C</sub> = 100°	°C)	2.4	Α	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	16	Α	
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	300	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)	4	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	4.8	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		48	W	
	- Derate above 25°C		0.38	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	9	-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	FQU5N50CTU_WS	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	110	°C/W

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQU5N50CTU-WS	FQU5N50CS	I-PAK	Tube	N/A	N/A	75 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Parameter	Test Conditions	Min	Тур	Max	Units
racteristics					
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	500			V
Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.5		V/°C
Zara Cata Valtaga Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			1	μА
Zero Gate voltage Drain Current	V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			10	μА
Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
	Practeristics Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward	racteristics         Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$ , $I_D = 250 \text{ μA}$ Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ μA}$ , Referenced to 25°C         Zero Gate Voltage Drain Current $V_{DS} = 500 \text{ V}$ , $V_{GS} = 0 \text{ V}$ $V_{DS} = 400 \text{ V}$ , $V_{CS} = 125 ^{\circ}\text{C}$ Gate-Body Leakage Current, Forward $V_{GS} = 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	racteristics         Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$ , $I_D = 250 \text{ μA}$ $500 $ Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ μA}$ , Referenced to $25^{\circ}$ C $$ $0.5$ Zero Gate Voltage Drain Current $V_{DS} = 500 \text{ V}$ , $V_{GS} = 0 \text{ V}$ $$ $$ Gate-Body Leakage Current, Forward $V_{GS} = 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$ $$ $$	racteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 250 \text{ μA}$ $500 $ Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ μA}, \text{ Referenced to } 25^{\circ}\text{C}$ $0.5 $ Zero Gate Voltage Drain Current $V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$ 1 $V_{DS} = 400 \text{ V}, T_C = 125^{\circ}\text{C}$ 10Gate-Body Leakage Current, Forward $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ 100

#### **On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.0 A		1.14	1.4	Ω
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 2.0 \text{ A}$		5.2		S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,	 480	625	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz	 80	105	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		 15	20	pF

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 250 V I <sub>D</sub> = 5 A	 12	35	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 250 \text{ V}, I_{D} = 5 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{G} = 25 \Omega$	 46	100	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		 50	110	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	 48	105	ns
$Q_g$	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 5 A,	 18	24	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V	 2.2		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)	 9.7		nC

## **Drain-Source Diode Characteristics and Maximum Ratings**

$I_S$	Maximum Continuous Drain-Source Diode Forward Current				4	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				16	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 4 A			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 5 \text{ A},$		263		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		1.9		μС

#### Notes:

- 1. Repetitive rating : pulse width limited by maximum junction temperature.
- 2. L = 21.5 mH, I $_{AS}$  = 5 A, V $_{DD}$  = 50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C.
- $3.~I_{SD} \leq 5~A,~di/dt \leq 200~A/\mu s,~V_{DD} \leq BV_{DSS,}~starting~~T_J = 25^{\circ}C.$
- ${\bf 4.} \ {\bf Essentially\ independent\ of\ operating\ temperature}.$

# **Typical Characteristics**

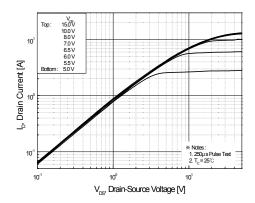


Figure 1. On-Region Characteristics

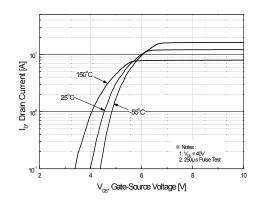


Figure 2. Transfer Characteristics

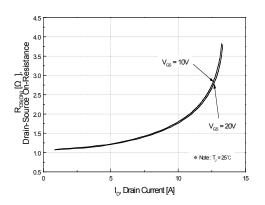


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

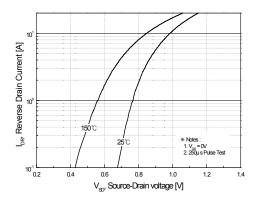


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

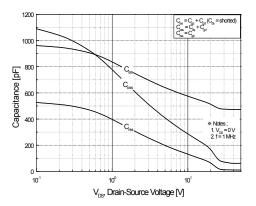


Figure 5. Capacitance Characteristics

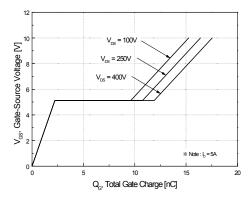


Figure 6. Gate Charge Characteristics

## Typical Characteristics (Continued)

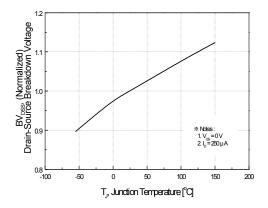


Figure 7. Breakdown Voltage Variation vs Temperature

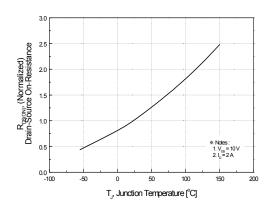


Figure 8. On-Resistance Variation vs Temperature

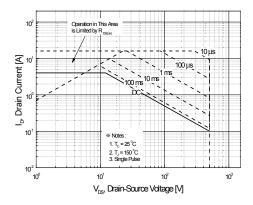


Figure 9. Maximum Safe Operating Area

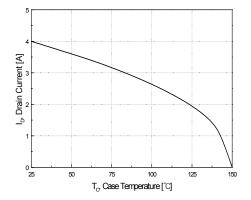


Figure 10. Maximum Drain Current vs Case Temperature

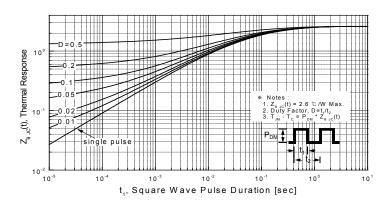


Figure 11. Transient Thermal Response Curve

Figure 12. Gate Charge Test Circuit & Waveform

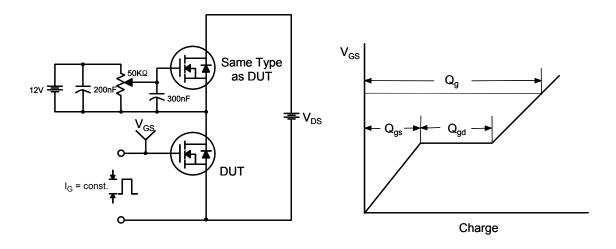


Figure 13. Resistive Switching Test Circuit & Waveforms

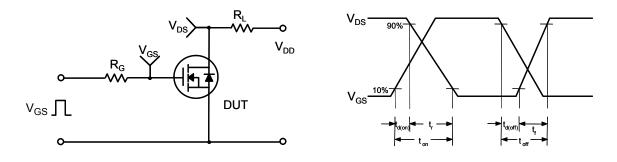


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

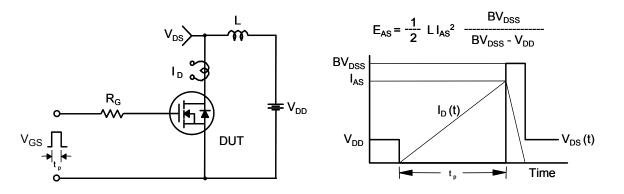
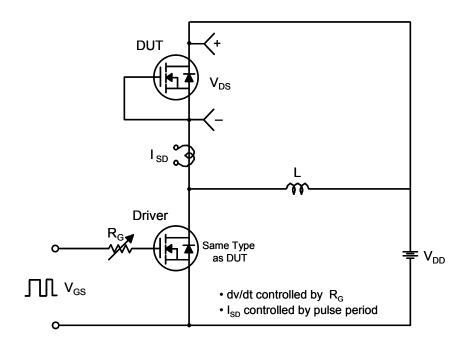
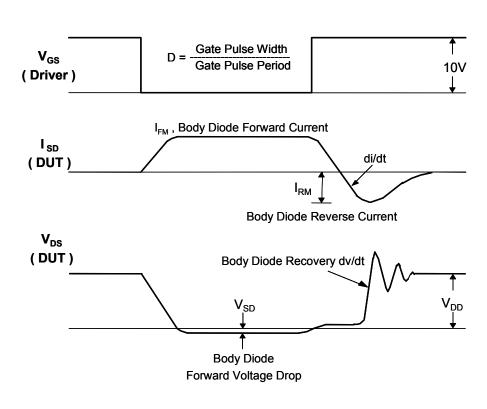


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





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